

Octal D Flip-Flop with 3-State Outputs

MC74AC574, MC74ACT574

The MC74AC574/74ACT574 is a high-speed, low power octal flip-flop with a buffered common Clock (CP) and a buffered common Output Enable ($\overline{OE}$). The information presented to the D inputs is stored in the flip-flops on the LOW-to-HIGH Clock (CP) transition.

The MC74AC574/74ACT574 is functionally identical to the MC74AC374/74ACT374 except for the pinouts.

Features

- Inputs and Outputs on Opposite Sides of Package Allowing Easy Interface with Microprocessors
- Useful as Input or Output Port for Microprocessors
- Functionally Identical to MC74AC374/74ACT374
- 3-State Outputs for Bus-Oriented Applications
- Outputs Source/Sink 24 mA
- 'ACT574 Has TTL Compatible Inputs
- Pb-Free Packages are Available

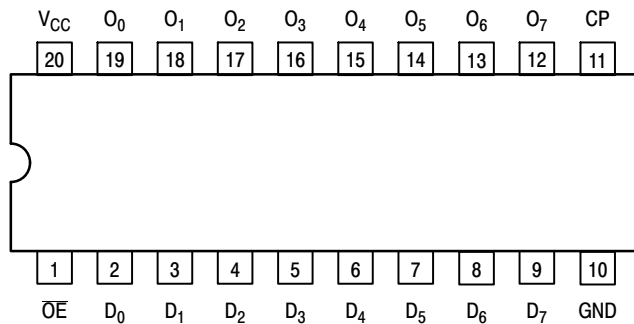


Figure 1. Pinout: 20-Lead Packages Conductors
(Top View)

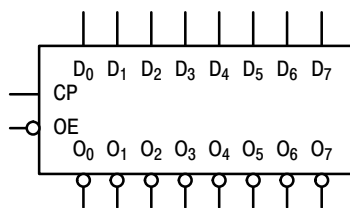
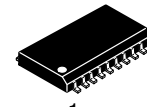


Figure 2. Logic Symbol

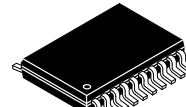
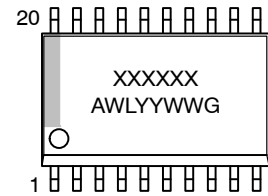
PIN ASSIGNMENT

PIN	FUNCTION
D ₀ -D ₇	Data Inputs
CP	Clock Pulse Input
$\overline{OE}$	3-State Output Enable Input
O ₀ -O ₇	3-State Outputs

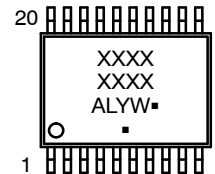
MARKING DIAGRAMS



SOIC-20W
DW SUFFIX
CASE 751D



TSSOP-20
DT SUFFIX
CASE 948E



XXXXXX = Specific Device Code

A = Assembly Location

WL, L = Wafer Lot

YY, Y = Year

WW, W = Work Week

G or ■ = Pb-Free Package

(Note: Microdot may be in either location)

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 7 of this data sheet.

MC74AC574, MC74ACT574

FUNCTIONAL DESCRIPTION

The MC74AC574/74ACT574 consists of eight edge-triggered flip-flops with individual D-type inputs and 3-state true outputs. The buffered clock and buffered Output Enable are common to all flip-flops. The eight flip-flops will store the state of their individual D inputs that meet the setup and hold time requirements on the LOW-to-HIGH Clock (CP) transition. With the Output Enable ($\overline{OE}$) LOW, the contents of the eight flip-flops are available at the outputs. When $\overline{OE}$ is HIGH, the outputs go to the high impedance state. Operation of the $\overline{OE}$ input does not affect the state of the flip-flops.

FUNCTION TABLE

Inputs			Internal	Outputs	Function
$\overline{OE}$	CP	D	Q	O_n	
H	H	L	NC	Z	Hold
H	H	H	NC	Z	Hold
H	$\lceil$	L	L	Z	Load
H	$\lceil$	H	H	Z	Load
L	$\lceil$	L	L	L	Data Available
L	$\lceil$	H	H	H	Data Available
L	H	L	NC	NC	No Change in Data
L	H	H	NC	NC	No Change in Data

H = HIGH Voltage Level

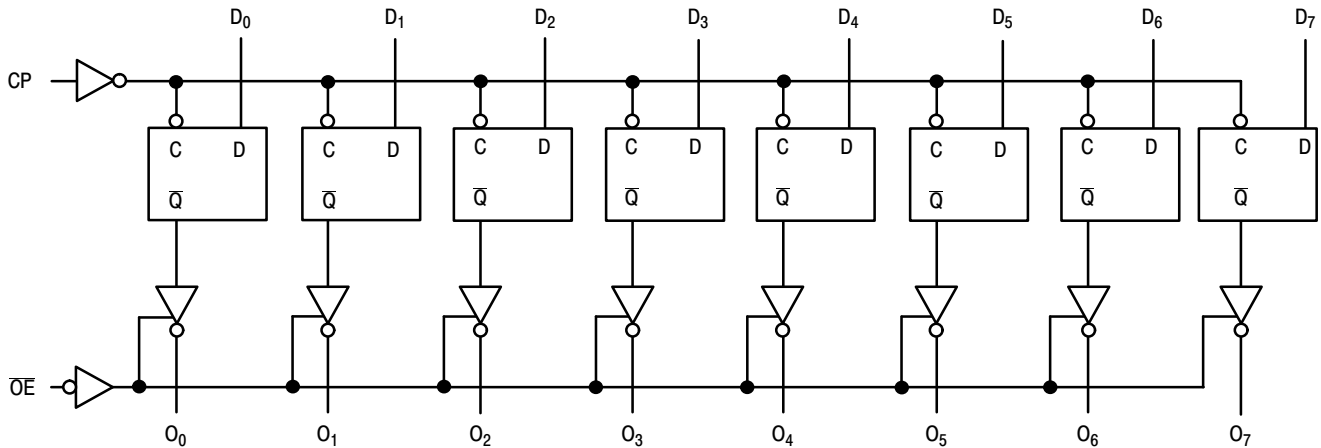
L = LOW Voltage Level

X = Immaterial

Z = High Impedance

$\lceil$ = LOW-to-HIGH Clock Transition

NC = No Change



NOTE: This diagram is provided only for the understanding of logic operations and should not be used to estimate propagation delays.

Figure 3. Logic Diagram

MC74AC574, MC74ACT574

MAXIMUM RATINGS

Symbol	Parameter	Value	Unit
V_{CC}	DC Supply Voltage (Referenced to GND)	-0.5 to +6.5	V
V_{IN}	DC Input Voltage (Referenced to GND)	-0.5 to $V_{CC} + 0.5$	V
V_{OUT}	DC Output Voltage (Referenced to GND)	-0.5 to $V_{CC} + 0.5$	V
I_{IN}	DC Input Current, per Pin	± 20	mA
I_{OUT}	DC Output Sink/Source Current, per Pin	± 50	mA
I_{CC}	DC V_{CC} or GND Current per Output Pin	± 50	mA
T_{stg}	Storage Temperature	-65 to +150	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min	Typ	Max	Unit
V_{CC}	Supply Voltage	'AC	2.0	5.0	V
		'ACT	4.5	5.0	
V_{IN}, V_{OUT}	DC Input Voltage, Output Voltage (Ref. to GND)	0	-	V_{CC}	V
t_r, t_f	Input Rise and Fall Time (Note 1) 'AC Devices except Schmitt Inputs	$V_{CC} @ 3.0\text{ V}$	-	150	ns/V
		$V_{CC} @ 4.5\text{ V}$	-	40	
		$V_{CC} @ 5.5\text{ V}$	-	25	
t_r, t_f	Input Rise and Fall Time (Note 2) 'ACT Devices except Schmitt Inputs	$V_{CC} @ 4.5\text{ V}$	-	10	ns/V
		$V_{CC} @ 5.5\text{ V}$	-	8.0	
T_A	Operating Ambient Temperature Range	-40	25	85	°C
I_{OH}	Output Current – High	-	-	-24	mA
I_{OL}	Output Current – Low	-	-	24	mA

1. V_{IN} from 30% to 70% V_{CC} ; see individual Data Sheets for devices that differ from the typical input rise and fall times.

2. V_{IN} from 0.8 V to 2.0 V; see individual Data Sheets for devices that differ from the typical input rise and fall times.

MC74AC574, MC74ACT574

DC CHARACTERISTICS

Symbol	Parameter	V _{CC} (V)	74AC		74AC		Unit	Conditions
			T _A = +25°C		T _A = -40°C to +85°C			
			Typ	Guaranteed Limits				
V _{IH}	Minimum High Level Input Voltage	3.0	1.5	2.1	2.1		V	V _{OUT} = 0.1 V or V _{CC} - 0.1 V
		4.5	2.25	3.15	3.15			
		5.5	2.75	3.85	3.85			
V _{IL}	Maximum Low Level Input Voltage	3.0	1.5	0.9	0.9		V	V _{OUT} = 0.1 V or V _{CC} - 0.1 V
		4.5	2.25	1.35	1.35			
		5.5	2.75	1.65	1.65			
V _{OH}	Minimum High Level Output Voltage	3.0	2.99	2.9	2.9		V	I _{OUT} = -50 μA
		4.5	4.49	4.4	4.4			
		5.5	5.49	5.4	5.4			
		3.0	-	2.56	2.46		V	*V _{IN} = V _{IL} or V _{IH} -12 mA I _{OH} -24 mA -24 mA
		4.5	-	3.86	3.76			
		5.5	-	4.86	4.76			
V _{OL}	Maximum Low Level Output Voltage	3.0	0.002	0.1	0.1		V	I _{OUT} = 50 μA
		4.5	0.001	0.1	0.1			
		5.5	0.001	0.1	0.1			
		3.0	-	0.36	0.44		V	*V _{IN} = V _{IL} or V _{IH} 12 mA I _{OL} 24 mA 24 mA
		4.5	-	0.36	0.44			
		5.5	-	0.36	0.44			
I _{IN}	Maximum Input Leakage Current	5.5	-	±0.1	±1.0		μA	V _I = V _{CC} , GND
I _{OLD}	†Minimum Dynamic Output Current	5.5	-	-	75		mA	V _{OLD} = 1.65 V Max
I _{OHD}		5.5	-	-	-75		mA	V _{OHD} = 3.85 V Min
I _{CC}	Maximum Quiescent Supply Current	5.5	-	8.0	80		μA	V _{IN} = V _{CC} or GND

* All outputs loaded; thresholds on input associated with output under test.

† Maximum test duration 2.0 ms, one output loaded at a time.

NOTE: Note: I_{IN} and I_{CC} @ 3.0 V are guaranteed to be less than or equal to the respective limit @ 5.5 V V_{CC}.

MC74AC574, MC74ACT574

AC CHARACTERISTICS (For Figures and Waveforms – See AND8277/D at www.onsemi.com)

Symbol	Parameter	V _{CC} * (V)	74AC			74AC		Unit	Fig. No.
			T _A = +25°C C _L = 50 pF			T _A = -40°C to +85°C C _L = 50 pF			
			Min	Typ	Max	Min	Max		
f _{max}	Maximum Clock Frequency	3.3 5.0	75 95	– –	– –	60 85	– –	MHz	3–3
t _{PLH}	Propagation Delay CP to O _n	3.3 5.0	3.5 2.0	– –	13.5 9.5	3.5 2.0	15 11	ns	3–6
t _{PHL}	Propagation Delay CP to O _n	3.3 5.0	3.5 2.0	– –	12 8.5	3.5 2.0	13.5 9.5	ns	3–6
t _{PZH}	Output Enable Time	3.3 5.0	2.5 2.0	– –	11 8.5	2.5 2.0	12 9.0	ns	3–7
t _{PZL}	Output Enable Time	3.3 5.0	3.0 1.5	– –	10.5 8.0	3.5 2.0	11.5 9.0	ns	3–8
t _{PHZ}	Output Disable Time	3.3 5.0	4.0 2.0	– –	12 9.5	4.5 2.0	13 10.5	ns	3–7
t _{PLZ}	Output Disable Time	3.3 5.0	2.0 1.5	– –	9.0 7.5	2.5 1.5	10 8.5	ns	3–8

*Voltage Range 3.3 V is 3.3 V ±0.3 V.

Voltage Range 5.0 V is 5.0 V ±0.5 V.

AC OPERATING REQUIREMENTS

Symbol	Parameter	V _{CC} * (V)	74AC		74AC	Unit	Fig. No.
			T _A = +25°C C _L = 50 pF		T _A = –40°C to +85°C C _L = 50 pF		
			Typ	Guaranteed Minimum			
t _s	Setup Time, HIGH or LOW D _n to CP	3.3	–	2.5	3.0	ns	3–9
		5.0	–	1.5	2.0		
t _h	Hold Time, HIGH or LOW D _n to CP	3.3	–	1.5	1.5	ns	3–9
		5.0	–	1.5	1.5		
t _w	CP Pulse Width HIGH or LOW	3.3	–	6.0	7.0	ns	3–6
		5.0	–	4.0	5.0		

*Voltage Range 3.3 V is 3.3 V ±0.3 V.

Voltage Range 5.0 V is 5.0 V ±0.5 V.

MC74AC574, MC74ACT574

DC CHARACTERISTICS

Symbol	Parameter	V _{CC} (V)	74ACT		74ACT		Unit	Conditions
			T _A = +25°C		T _A = -40°C to +85°C			
			Typ	Guaranteed Limits				
V _{IH}	Minimum High Level Input Voltage	4.5 5.5	1.5 1.5	2.0 2.0	2.0 2.0	V	V _{OUT} = 0.1 V or V _{CC} - 0.1 V	
V _{IL}	Maximum Low Level Input Voltage	4.5 5.5	1.5 1.5	0.8 0.8	0.8 0.8	V	V _{OUT} = 0.1 V or V _{CC} - 0.1 V	
V _{OH}	Minimum High Level Output Voltage	4.5 5.5	4.49 5.49	4.4 5.4	4.4 5.4	V	I _{OUT} = -50 μA	
		4.5 5.5	- -	3.86 4.86	3.76 4.76	V	*V _{IN} = V _{IL} or V _{IH} I _{OH} -24 mA -24 mA	
		4.5 5.5	- -	0.36 0.36	0.44 0.44	V	*V _{IN} = V _{IL} or V _{IH} 24 mA I _{OL} 24 mA	
V _{OL}	Maximum Low Level Output Voltage	4.5 5.5	0.001 0.001	0.1 0.1	0.1 0.1	V	I _{OUT} = 50 μA	
		4.5 5.5	- -	0.36 0.36	0.44 0.44	V	*V _{IN} = V _{IL} or V _{IH} 24 mA I _{OL} 24 mA	
		4.5 5.5	- -	0.36 0.36	0.44 0.44	V	*V _{IN} = V _{IL} or V _{IH} 24 mA I _{OL} 24 mA	
I _{IN}	Maximum Input Leakage Current	5.5	-	±0.1	±1.0	μA	V _I = V _{CC} , GND	
ΔI _{CCT}	Additional Max. I _{CC} /Input	5.5	0.6		1.5	mA	V _I = V _{CC} - 2.1 V	
I _{OZ}	Maximum 3-State Current	5.5	-	±0.5	±5.0	μA	V _I (OE) = V _{IL} , V _{IH} V _I = V _{CC} , GND V _O = V _{CC} , GND	
I _{OLD}	†Minimum Dynamic Output Current	5.5	-	-	75	mA	V _{OLD} = 1.65 V Max	
I _{OHD}		5.5	-	-	-75	mA	V _{OHD} = 3.85 V Min	
I _{CC}	Maximum Quiescent Supply Current	5.5	-	8.0	80	μA	V _{IN} = V _{CC} or GND	

*All outputs loaded; thresholds on input associated with output under test.

†Maximum test duration 2.0 ms, one output loaded at a time.

AC CHARACTERISTICS (For Figures and Waveforms – See AND8277/D at www.onsemi.com)

Symbol	Parameter	V _{CC} * (V)	74ACT			74ACT		Unit	Fig. No.
			T _A = +25°C C _L = 50 pF			T _A = -40°C to +85°C C _L = 50 pF			
			Min	Typ	Max	Min	Max		
f _{max}	Maximum Clock Frequency	5.0	100	–	–	85	–	ns	3–3
t _{PLH}	Propagation Delay CP to O _n	5.0	2.5	–	11	2.0	12	ns	3–6
t _{PHL}	Propagation Delay CP to O _n	5.0	2.0	–	10	1.5	11	ns	3–6
t _{PZH}	Output Enable Time	5.0	2.0	–	9.5	1.5	10	ns	3–7
t _{PZL}	Output Enable Time	5.0	2.0	–	9.0	1.5	10	ns	3–8
t _{PHZ}	Output Disable Time	5.0	2.0	–	10.5	1.5	11.5	ns	3–7
t _{PLZ}	Output Disable Time	5.0	2.0	–	8.5	1.5	9.0	ns	3–8

*Voltage Range 5.0 V is 5.0 V ±0.5 V.

MC74AC574, MC74ACT574

AC OPERATING REQUIREMENTS

Symbol	Parameter	V _{CC} * (V)	74ACT		74ACT	Unit	Fig. No.
			T _A = +25°C C _L = 50 pF		T _A = -40°C to +85°C C _L = 50 pF		
			Typ	Guaranteed Minimum			
t _s	Setup Time, HIGH or LOW D _n to CP	5.0	–	2.5	2.5	ns	3–9
t _h	Hold Time, HIGH or LOW D _n to CP	5.0	–	1.0	1.0	ns	3–9
t _w	CP Pulse Width HIGH or LOW	5.0	–	3.0	4.0	ns	3–6

*Voltage Range 3.3 V is 3.3 V ±0.3 V.

Voltage Range 5.0 V is 5.0 V ±0.5 V.

CAPACITANCE

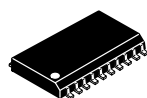
Symbol	Parameter	Value Typ	Unit	Test Conditions
C _{IN}	Input Capacitance	4.5	pF	V _{CC} = 5.0 V
C _{PD}	Power Dissipation Capacitance	40	pF	V _{CC} = 5.0 V

ORDERING INFORMATION

Device	Marking	Package	Shipping [†]
MC74AC574DWG	AC574	SOIC–20	38 Units / Rail
MC74AC574DWR2G	AC574	SOIC–20	1000 / Tape & Reel
MC74ACT574DWG	ACT574	SOIC–20	38 Units / Rail
MC74ACT574DWR2G	ACT574	SOIC–20	1000 / Tape & Reel
MC74AC574DTR2G	AC 574	TSSOP–20	2500 / Tape & Reel
MC74ACT574DTR2G	ACT 574	TSSOP–20	2500 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

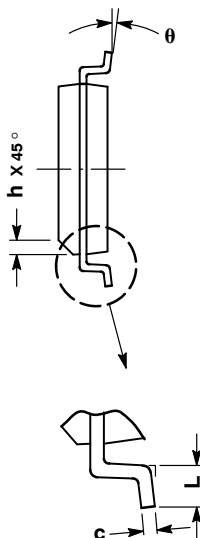
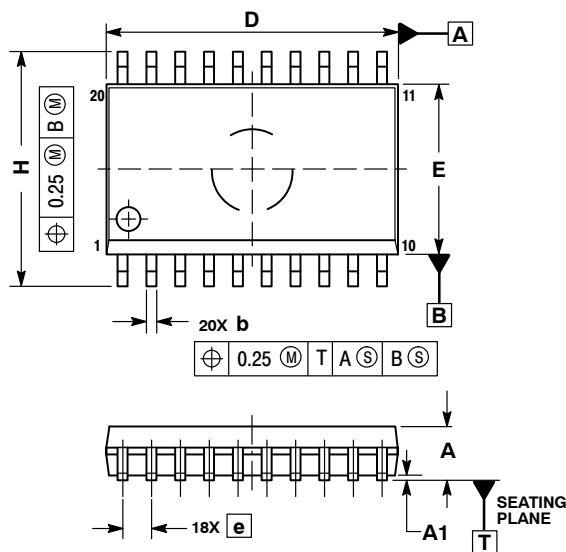
MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS



SCALE 1:1

SOIC-20 WB
CASE 751D-05
ISSUE H

DATE 22 APR 2015

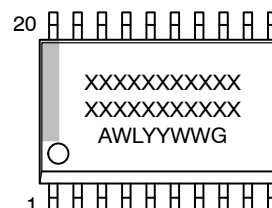


NOTES:

1. DIMENSIONS ARE IN MILLIMETERS.
2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 1994.
3. DIMENSIONS D AND E DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15 PER SIDE.
5. DIMENSION B DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE PROTRUSION SHALL BE 0.13 TOTAL IN EXCESS OF B DIMENSION AT MAXIMUM MATERIAL CONDITION.

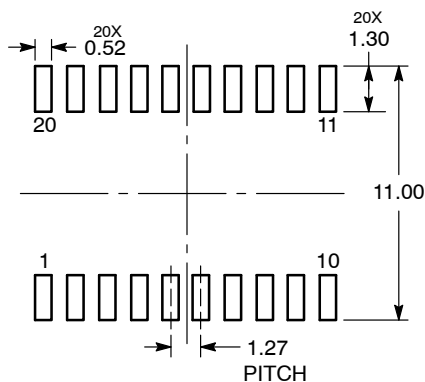
DIM	MILLIMETERS	
	MIN	MAX
A	2.35	2.65
A1	0.10	0.25
b	0.35	0.49
c	0.23	0.32
D	12.65	12.95
E	7.40	7.60
e	1.27 BSC	
H	10.05	10.55
h	0.25	0.75
L	0.50	0.90
θ	0°	7°

GENERIC MARKING DIAGRAM*



XXXXXX = Specific Device Code
A = Assembly Location
WL = Wafer Lot
YY = Year
WW = Work Week
G = Pb-Free Package

RECOMMENDED SOLDERING FOOTPRINT*



DIMENSIONS: MILLIMETERS

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

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DESCRIPTION:	SOIC-20 WB	PAGE 1 OF 1

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MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

ON Semiconductor®

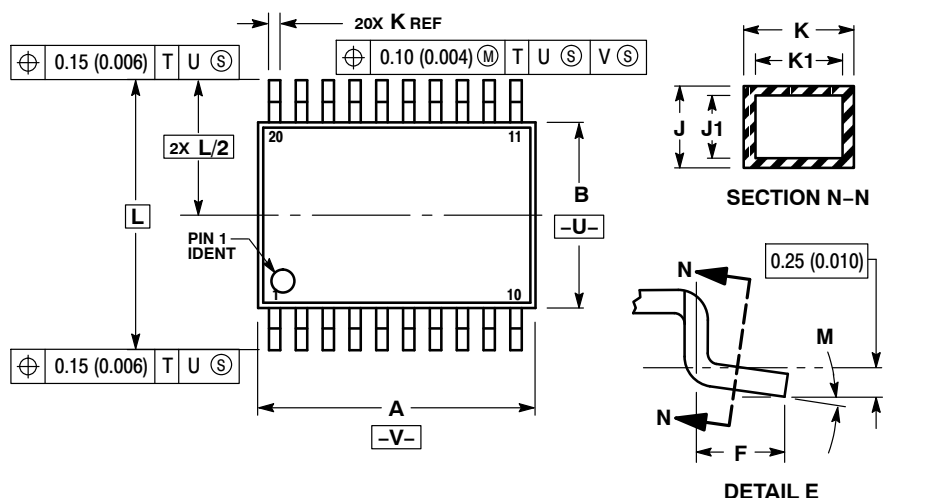
ON



SCALE 2:1

TSSOP-20 WB
CASE 948E
ISSUE D

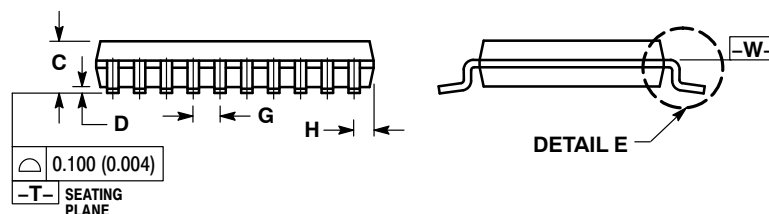
DATE 17 FEB 2016



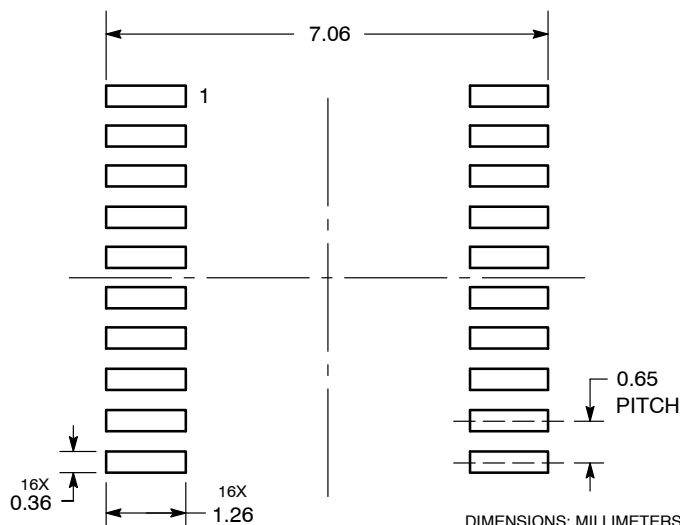
NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSION A DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
5. DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION.
6. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
7. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE -W-.

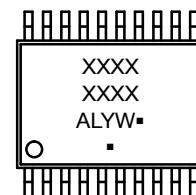
DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	6.40	6.60	0.252	0.260
B	4.30	4.50	0.169	0.177
C	---	1.20	---	0.047
D	0.05	0.15	0.002	0.006
F	0.50	0.75	0.020	0.030
G	0.65 BSC		0.026 BSC	
H	0.27	0.37	0.011	0.015
J	0.09	0.20	0.004	0.008
J1	0.09	0.16	0.004	0.006
K	0.19	0.30	0.007	0.012
K1	0.19	0.25	0.007	0.010
L	6.40 BSC		0.252 BSC	
M	0°	8°	0°	8°



SOLDERING FOOTPRINT



GENERIC MARKING DIAGRAM*



- A = Assembly Location
- L = Wafer Lot
- Y = Year
- W = Work Week
- = Pb-Free Package

(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present.

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